



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC009NE2LS5		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001219500						
<b>Package</b>		PG-TDSON-8-7		<b>Weight*</b>		115.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.635	0.55	0.55	5479	5479
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		424	
	non noble metal	copper	7440-50-8	49.082	42.33	42.38	423336	423887
	non noble metal	copper	7440-50-8	0.021	0.02	0.02	179	179
wire	non noble metal	copper	7440-50-8	0.021	0.02	0.02	179	179
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		712	
	plastics	epoxy resin	-	5.857	5.05		50518	
	inorganic material	silicondioxide	60676-86-0	35.307	30.45	35.57	304528	355758
leadfinish	non noble metal	tin	7440-31-5	1.452	1.25	1.25	12521	12521
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1428	1428
solder	non noble metal	tin	7440-31-5	0.019	0.02		165	
	noble metal	silver	7440-22-4	0.024	0.02		206	
	non noble metal	lead	7439-92-1	0.911	0.79	0.83	7858	8229
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		58	
	non noble metal	iron	7439-89-6	0.022	0.02		193	
	non noble metal	copper	7440-50-8	22.292	19.23	19.26	192268	192519
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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